

VE320 Homework Nine

Due: 2021/8/6 23:59

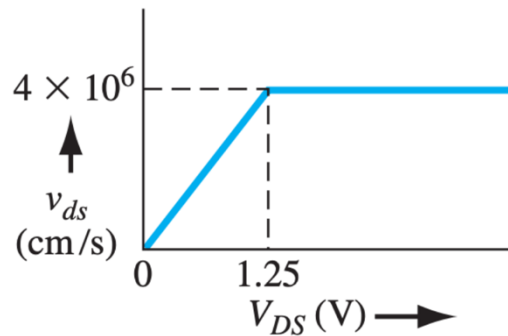
(Note: In the following problems, assume the semiconductor and oxide in the MOS system are silicon and silicon dioxide, respectively, and assume the temperature is $T = 300\text{ K}$ unless otherwise stated.)

1. Assume that the subthreshold current of a MOSFET is given by

$$I_D = 10^{-15} \exp\left(\frac{V_{GS}}{(2.1)V_t}\right)$$

over the range $0 \leq V_{GS} \leq 1$ volt and where the factor 2.1 takes into account the effect of interface states. Assume that 10^6 identical transistors on a chip are all biased at the same V_{GS} and at $V_{DD} = 5\text{ V}$.

- (a) Calculate the total current that must be supplied to the chip at $V_{GS} = 0.5, 0.7$, and 0.9 V .
 - (b) Calculate the total power dissipated in the chip for the same V_{GS} values.
2. Consider an n-channel silicon MOSFET. The parameters are $k'_n = 75\mu\text{A/V}^2$, $W/L = 10$, and $V_T = 0.35\text{ V}$. The applied drain-to-source voltage is $V_{DS} = 1.5\text{ V}$
 - (a) For $V_{GS} = 0.8\text{ V}$, find (i) the ideal drain current, (ii) the drain current if $\lambda = 0.02\text{ V}^{-1}$, and (iii) the output resistance for $\lambda = 0.02\text{ V}^{-1}$.
 - (b) Repeat part (a) for $V_{GS} = 1.25\text{ V}$.
 3. The parameters of an n-channel enhancement-mode MOSFET are $V_T = 0.40\text{ V}$, $t_{ox} = 20\text{ nm} = 200\text{ \AA}$, $L = 1.0\mu\text{m}$, and $W = 10\mu\text{m}$.
 - (a) Assuming a constant mobility of $\mu_n = 475\text{ cm}^2/\text{V} \cdot \text{s}$, calculate I_D for $V_{GS} - V_T = 2.0\text{ V}$ when biased at (i) $V_{DS} = 0.5\text{ V}$, (ii) $V_{DS} = 1.0\text{ V}$, (iii) $V_{DS} = 1.25\text{ V}$ and (iv) $V_{DS} = 2.0\text{ V}$
 - (b) Consider the piecewise linear model of the carrier velocity versus V_{DS} shown in the figure below. Calculate I_D for the same voltage values given in part (a). [See equation $I_D(\text{sat}) = WC_{ox}(V_{GS} - V_T)v_{\text{sat}}$]
 - (c) Determine the $V_{DS}(\text{sat})$ values for parts (a) and (b).



(Note: In the following problems, use the transistor geometry shown in Figure

12.13. Assume $T = 300\text{ K}$ unless otherwise stated.)

4. Consider a $p^{++}n^+p$ bipolar transistor, uniformly doped in each region. Sketch the energy-band diagram for the case when the transistor is
 - (a) in thermal equilibrium,
 - (b) biased in the forward-active mode,
 - (c) biased in the inverse-active region, and
 - (d) biased in cutoff with both the $B - E$ and $B - C$ junctions reverse biased.

5. A uniformly doped silicon npn bipolar transistor at $T = 300\text{ K}$ is biased in the forward-active mode. The doping concentrations are $N_E = 8 \times 10^{17}\text{ cm}^{-3}$, $N_B = 2 \times 10^{16}\text{ cm}^{-3}$, and $N_C = 10^{15}\text{ cm}^{-3}$.
 - (a) Determine the thermal-equilibrium values p_{E0} , n_{B0} , and p_{C0} .
 - (b) For $V_{BE} = 0.640\text{ V}$, calculate the values of n_B at $x = 0$ and p_E at $x' = 0$.
 - (c) Sketch the minority carrier concentrations through the device and label each curve.

6. A uniformly doped pnp silicon bipolar transistor has a base doping of $N_B = 10^{16}\text{ cm}^{-3}$, a collector doping of $N_C = 10^{15}\text{ cm}^{-3}$, a metallurgical base width of $x_{B0} = 0.70\mu\text{m}$, a base minority carrier diffusion coefficient of $D_B = 10\text{ cm}^2/\text{s}$, and a B-E cross-sectional area of $A_{BE} = 10^{-4}\text{ cm}^2$. The transistor is biased in the forward-active mode with $V_{EB} = 0.625\text{ V}$. Neglecting the $B - E$ space charge width and assuming $x_B \ll L_B$,
 - (a) determine the change in neutral base width as V_{BC} changes from 1 to 5 V,
 - (b) find the corresponding change in collector current,
 - (c) estimate the Early voltage
 - (d) find the output resistance.